

ABSTRACT

A method for fabricating arbitrarily configured arrays of devices or circuit modules onto a host circuit substrate by using an assembly technique that temporarily locates and aligns the devices or circuit modules in positions to be received by the host circuit substrate.

- 5 The method generally comprises four distinct steps. The first step comprises fabricating the individual devices and circuit modules in a manner that facilitates capture of the individual devices and/or modules by an assembly template. The second step comprises patterning the assembly template to provide receptacles or patterned coatings that capture the devices and modules in the appropriate orientation. The third step comprises the population of the
- 10 assembly template with the devices and circuit modules. The fourth step comprises delivery of the device and circuit modules to the host circuit substrate.